

COMPANY	Electroglas' innovative wafer probers, prober-based test handlers, test floor management software and services improve the overall effectiveness of semiconductor wafer and device testing processes by delivering faster answers to critical questions about device quality, manufacturing performance and corrective action needed. Headquartered in San Jose, California, the company has been a leading equipment supplier to the semiconductor industry for over four decades, and has shipped more than 15,000 systems worldwide.
STOCK SYMBOL	EGLS (Nasdaq)
MANAGEMENT	Tom Rohrs, Chairman of the Board and Chief Executive Officer Thomas Brunton, Vice President of Finance, CFO, Treasurer and Secretary Richard J. Casler, Vice President of Engineering Wes Highfill, Vice President of Global Sales and Marketing Wayne Woodard, Vice President of Service and Operations
CUSTOMERS	Leading global semiconductor companies, including, Intel, Texas Instruments, ST Microelectronics, Micron, Philips, ASET, Amkor and Cypress..
PRODUCTS	<p><b>Wafer Probers</b></p> <p>Electroglas was the first company to produce a production worthy automatic wafer prober. Our range of 200mm and 300mm probers were the first to offer such breakthroughs as frictionless motion, non-contact edge sensing and fiducial alignment, helping customers optimize their manufacturing process and achieve better yields. This innovation continues today, as Electroglas moves to build on its proven probing technology to meet the evolving needs of semiconductor wafer and device testing for dynamic random access memory (DRAM), flash memory, system-on-a-chip (SOC), logic and other devices.</p> <p><i>300mm Wafer Probers</i> EG6000, EG6000e</p> <p><i>100-200mm Wafer Probers</i> 4090µ+ and 4090µ Fast Probe</p> <p><b>Prober-based Test Handlers</b></p> <p>Electroglas test handlers are built upon proven prober technology to give chipmakers a fast, flexible handling solution for today's latest packaging technologies, including Wafer Level Packages (WLP), Known-Good Die (KGD), Microelectromechanical Systems (MEMS), ultra-thin and/or diced wafers, as well as any packages in strip, panel or leadframe format. Delivering greater speed and accuracy than traditional handling methodologies, Electroglas provides automated, very high speed parallel test handling solutions that accommodate most leading edge device packaging technologies – simplifying the final test process. This allows chipmakers to maximize profitability by increasing test cell throughput and allowing them to handle the tightest new package geometries.</p> <p><i>For Test on Dicing Frame</i> Pathfinder</p>

**Test Floor Management Software**

Electroglas test floor management software provides a unique, networked solution to connect wafer probers and test handlers to the broader testing infrastructure, allowing the chipmaker to better manage overall test effectiveness by more accurately and efficiently monitoring, analyzing and improving important processes. Within a secure, web-based environment, Electroglas offers automated data collection, analysis, and alarming for corrective action. Results are delivered via dynamic, interactive web pages that match presentation and interaction expectations with the audience, allowing users to view reports and/or perform additional analysis.

*Web-based Test Floor Management*  
SORTmanager

FINANCIALS      Fiscal year end: May 31, 2006  
FY2004 revenue: \$63M

OPERATIONS      264 employees worldwide

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Other offices are located throughout the United States as well as in Europe and Asia.

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